

APT1002RBN	1000V	7.0A	2.00Ω
APT902RBN	900V	7.0A	2.00Ω
APT1002R4BN	1000V	6.5A	2.40Ω
APT902R4BN	900V	6.5A	2.40Ω

## POWER MOS IV®

### N-CHANNEL ENHANCEMENT MODE HIGH VOLTAGE POWER MOSFETS

#### MAXIMUM RATINGS

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT				UNIT
		902RBN	1002RBN	902R4BN	1002R4BN	
$V_{DSS}$	Drain-Source Voltage	900	1000	900	1000	Volts
$I_D$	Continuous Drain Current	7.0		6.5		Amps
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	28		26		Amps
$V_{GS}$	Gate-Source Voltage	±30				Volts
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$ , Derate Above $25^\circ\text{C}$	240				Watts
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	- 55 to 150				$^\circ\text{C}$

#### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions / Part Number	MIN	TYP	MAX	UNIT	
$BV_{DSS}$	Drain-Source Breakdown Voltage ( $V_{GS} = 0V, I_D = 250 \mu\text{A}$ )	APT1002RBN / APT1002R4BN	1000			Volts
		APT902RBN / APT902R4BN	900			Volts
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{DS} = V_{DSS}, V_{GS} = 0V$ ) ( $V_{DS} = 0.8 V_{DSS}, V_{GS} = 0V, T_C = 125^\circ\text{C}$ )			250	$\mu\text{A}$	
				1000		
$I_{GSS}$	Gate-Source Leakage Current ( $V_{GS} = \pm 30V, V_{DS} = 0V$ )			±100	nA	
$I_D(ON)$	On State Drain Current <sup>②</sup> ( $V_{DS} > I_D(ON) \times R_{DS(ON)}$ Max, $V_{GS} = 10V$ )	APT1002RBN / APT902RBN	7.0			Amps
		APT1002R4BN / APT902R4BN	6.5			Amps
$V_{GS(TH)}$	Gate Threshold Voltage ( $V_{DS} = V_{GS}, I_D = 1\text{mA}$ )	2		4	Volts	
$R_{DS(ON)}$	Static Drain-Source On-State Resistance <sup>②</sup> ( $V_{GS} = 10V, I_D = 0.5 I_D[\text{Cont.}]$ )	APT1002RBN / APT902RBN			2.00	Ohms
		APT1002R4BN / APT902R4BN			2.40	Ohms

#### THERMAL CHARACTERISTICS

[www.DataSheet4U.com](http://www.DataSheet4U.com)

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.51	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction to Ambient			40	$^\circ\text{C/W}$
$T_L$	Max. Lead Temp. for Soldering Conditions: 0.063" from Case for 10 Sec.			300	$^\circ\text{C}$

**CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		1530	1800	pF
$C_{oss}$	Output Capacitance			230	325	pF
$C_{rss}$	Reverse Transfer Capacitance			80	120	pF
$Q_g$	Total Gate Charge <sup>③</sup>	$V_{GS} = 10V, I_D = I_D [\text{Cont.}]$ $V_{DD} = 0.5 V_{DSS}$		66	105	nC
$Q_{gs}$	Gate-Source Charge			6.5	10	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge			36	54	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 0.5 V_{DSS}$ $I_D = I_D [\text{Cont.}], V_{GS} = 15V$ $R_G = 1.8\Omega$		14	28	ns
$t_r$	Rise Time			13	26	ns
$t_{d(off)}$	Turn-off Delay Time			55	82	ns
$t_f$	Fall Time			19	37	ns

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions / Part Number	MIN	TYP	MAX	UNIT
$I_S$	Continuous Source Current (Body Diode)	APT1002RBN / APT902RBN		7.0	Amps
		APT1002R4BN / APT902R4BN		6.5	Amps
$I_{SM}$	Pulsed Source Current <sup>①</sup> (Body Diode)	APT1002RBN / APT902RBN		28	Amps
		APT1002R4BN / APT902R4BN		26	Amps
$V_{SD}$	Diode Forward Voltage <sup>②</sup> ( $V_{GS} = 0V, I_S = -I_D [\text{Cont.}]$ )			1.3	Volts
$t_{rr}$	Reverse Recovery Time ( $I_S = -I_D [\text{Cont.}], di_S/dt = 100A/\mu s$ )	225	450	910	ns
$Q_{rr}$	Reverse Recovery Charge	1.2	2.5	5	$\mu C$

SAFE OPERATING AREA CHARACTERISTICS

Symbol	Characteristic	Test Conditions / Part Number	MIN	TYP	MAX	UNIT
SOA1	Safe Operating Area	$V_{DS} = 0.4 V_{DSS}, I_{DS} = P_D / 0.4 V_{DSS}, t = 1\text{ Sec.}$	240			Watts
SOA2	Safe Operating Area	$I_{DS} = I_D [\text{Cont.}], V_{DS} = P_D / I_D [\text{Cont.}], t = 1\text{ Sec.}$	240			Watts
$I_{LM}$	Inductive Current Clamped	APT1002RBN / APT902RBN	28			Amps
		APT1002R4BN / APT902R4BN	26			Amps

① Repetitive Rating: Pulse width limited by maximum junction temperature. See Transient Thermal Impedance Curve. (Fig.1)

② Pulse Test: Pulse width < 380  $\mu s$ , Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

APT Reserves the right to change, without notice, the specifications and information contained herein.

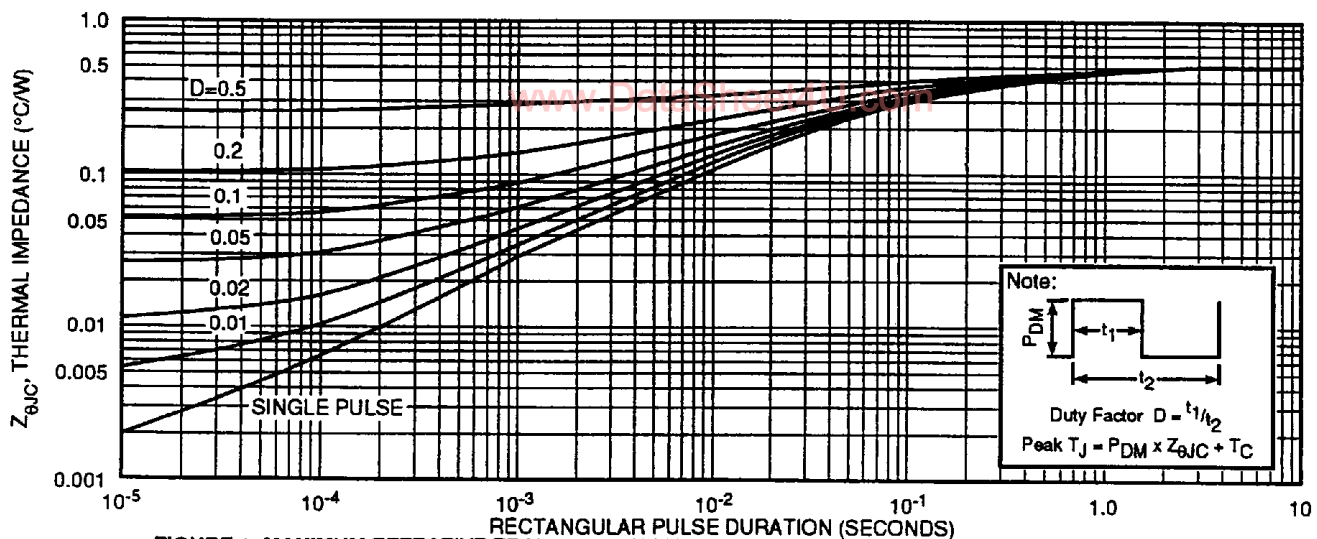
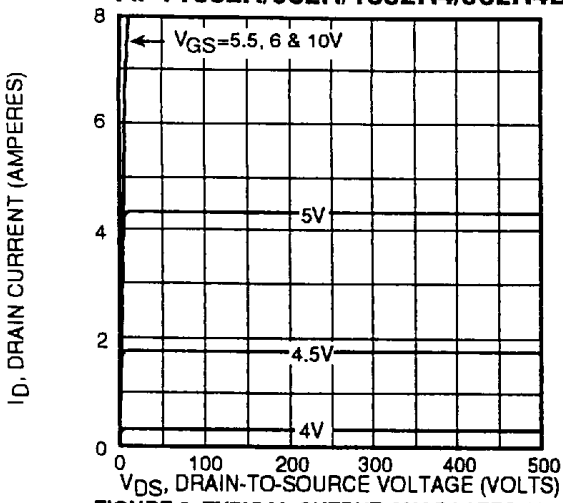
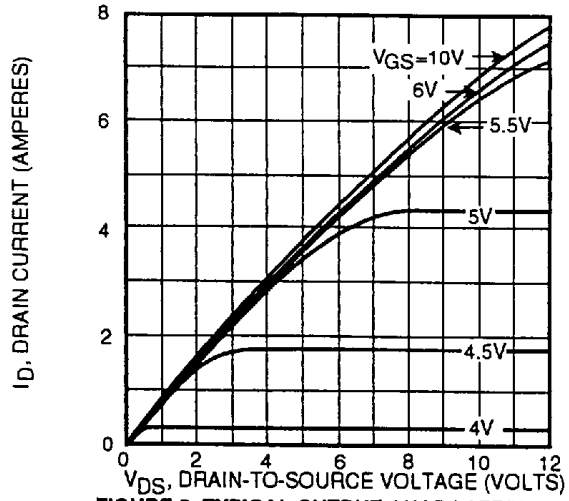


FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION

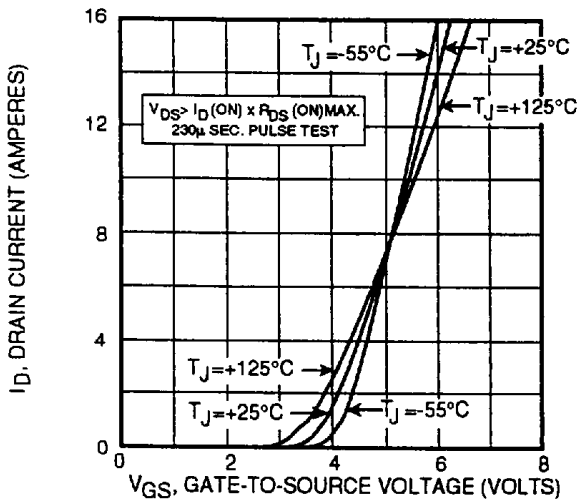
**APT1002R/902R/1002R4/902R4BN**



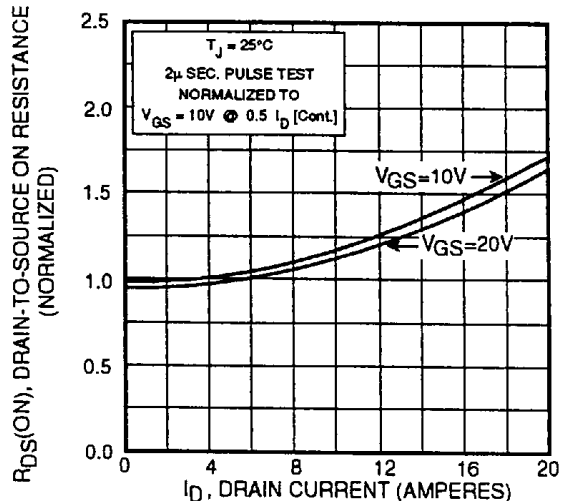
**FIGURE 2, TYPICAL OUTPUT CHARACTERISTICS**



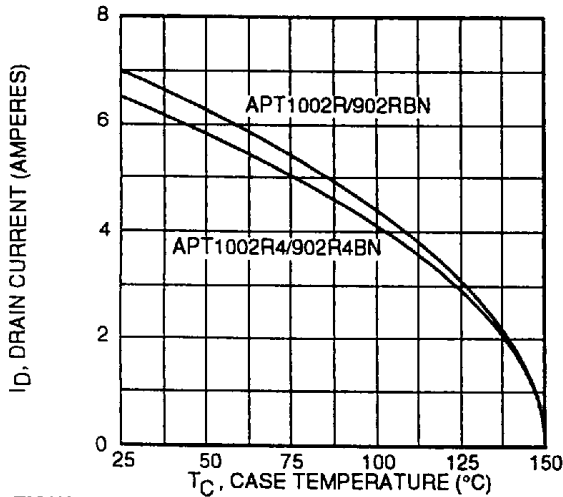
**FIGURE 3, TYPICAL OUTPUT CHARACTERISTICS**



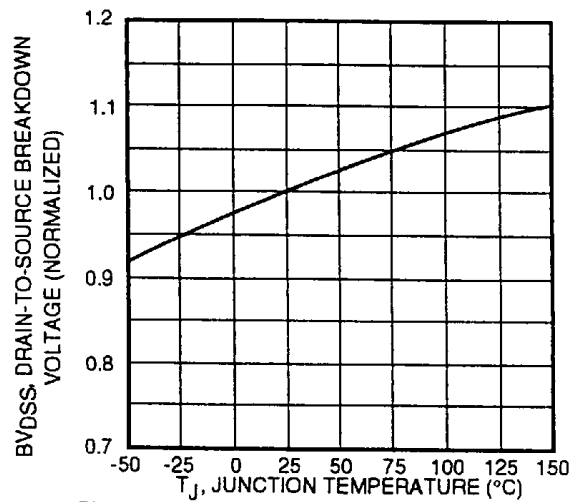
**FIGURE 4, TYPICAL TRANSFER CHARACTERISTICS**



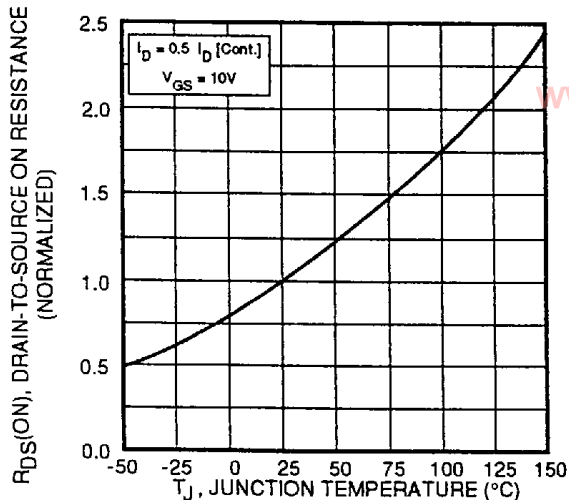
**FIGURE 5, RDS(ON) vs DRAIN CURRENT**



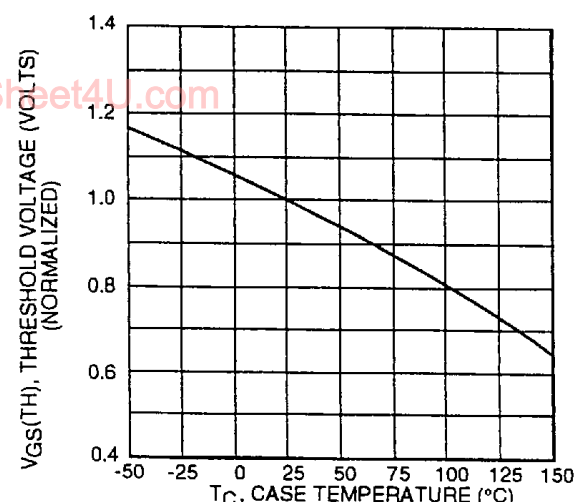
**FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE**



**FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE**



**FIGURE 8, ON-RESISTANCE vs. TEMPERATURE**



**FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE**

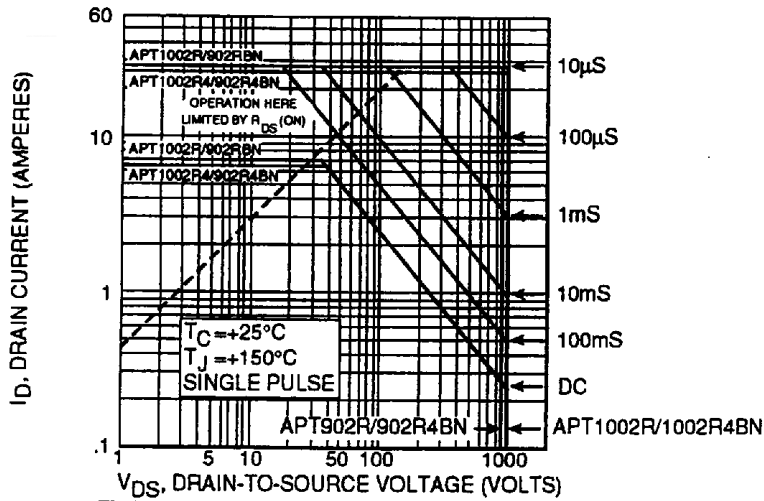


FIGURE 10, MAXIMUM SAFE OPERATING AREA

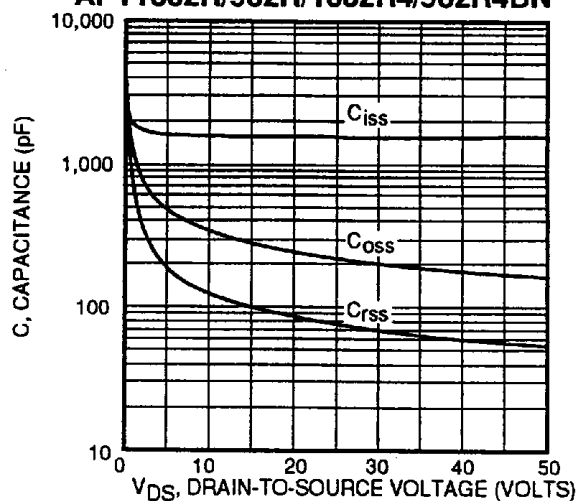


FIGURE 11, TYPICAL CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

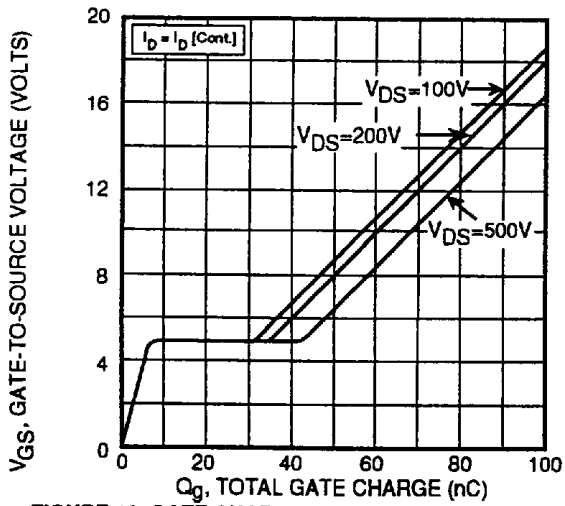


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

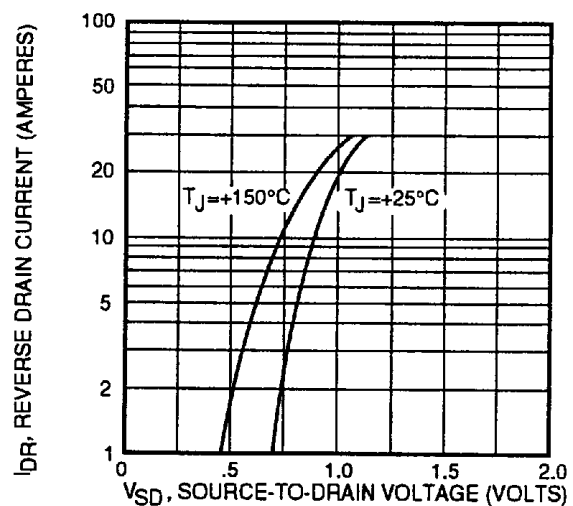


FIGURE 13, TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

TO-247AD Package Outline

